



flow90CON 1

1600 V / 36 A

Topology features

- Three-phase Half Controlled Converter
- Open Emitter configuration
- Brake Chopper

Component features

- High inrush current capability

Housing features

- Base isolation: Al₂O₃
- 90° mounting angle between heatsink and PCB
- Screw-on heatsink mounting
- Clip-in PCB mounting
- Thermo-mechanical push-and-pull force relief
- Solder pin

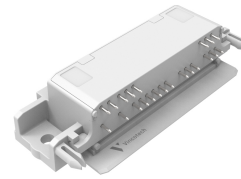
Target applications

- Motor drives
- Servo drives

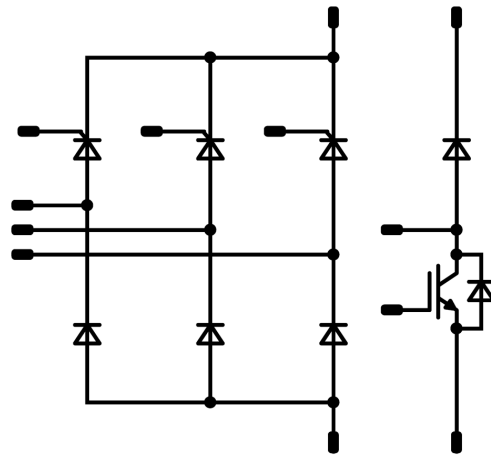
Types

- V23990-P717-G10-PM

flow90 1 housing



Schematic





Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Brake Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	31	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	75	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	65	W
Gate-emitter voltage	V_{GES}		± 20	V
Maximum junction temperature	T_{jmax}		150	°C

Brake Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	15	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	15	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	33	W
Maximum junction temperature	T_{jmax}		150	°C

Brake Sw. Protection Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	10	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	6	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	25	W
Maximum junction temperature	T_{jmax}		150	°C



Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Rectifier Thyristor				
Repetitive peak reverse voltage	V_{RRM}		1200	V
Maximum RMS on-state current	I_{TRMSM}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	45	A
Surge on-state current	I_{ISM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	360	A
I2t value	I^2t	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	650	A ² s
Mean total power loss	$P_{tot(AV)}$	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	68	W
Maximum Junction Temperature	T_{jmax}		150	°C

Rectifier Diode

Peak repetitive reverse voltage	V_{RRM}		1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	63	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	520	A
Surge current capability	I^2t		1350	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	73	W
Maximum junction temperature	T_{jmax}		150	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Creepage distance			>12,7	mm
Clearance			11,84	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,001	25	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		25	25 125	1,35	1,63 1,84	2,05 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			150	μA
Gate-emitter leakage current	I_{GES}		20	0		25			600	nA
Internal gate resistance	r_g							8		Ω
Input capacitance	C_{ies}							1808		pF
Output capacitance	C_{oes}	$f = 1$ Mhz	0	25		25		95		pF
Reverse transfer capacitance	C_{res}							82		pF

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,08		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 32$ Ω $R_{goff} = 16$ Ω	0/15	600	15	25		64,64		ns
Rise time	t_r					125		62,08		ns
						25		26,24		ns
Turn-off delay time	$t_{d(off)}$					25		461,44		ns
						125		579,52		ns
Fall time	t_f					25		60,79		ns
		125		122,42		ns				
Turn-on energy (per pulse)	E_{on}	$Q_{trFD} = 1,09$ μC		25		0,972		mWs		
		$Q_{trFD} = 2,02$ μC		125		1,22		mWs		
Turn-off energy (per pulse)	E_{off}			25		1,03		mWs		
				125		1,74		mWs		



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Diode

Static

Forward voltage	V_F				7,5	25 125	1,23	1,63 1,59	1,97 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V				25			27	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,12		K/W
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Dynamic

Peak recovery current	I_{RM}	$di/dt=548$ A/μs $di/dt=567$ A/μs	0/15	600	15	25		8,34		A
						125		10,54		
Reverse recovery time	t_{rr}					25		383,53		ns
						125		582,52		
Recovered charge	Q_r					25		1,09		μC
		125		2,02						
Reverse recovered energy	E_{rec}	25		0,457		mWs				
		125		0,902						
Peak rate of fall of recovery current	$(di/dt)_{max}$	25		95,78		A/μs				
		125		51,87						

Brake Sw. Protection Diode

Static

Forward voltage	V_F				3	25 125	1,23	1,61 1,58	1,97 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V				25			27	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,8		K/W
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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Rectifier Thyristor

Static

On-state voltage	V_T				45	25 125		1,54 1,66	1,4 ⁽¹⁾ 1,45 ⁽¹⁾	V
Direct reverse current	I_{RD}	$V_r = 1200$ V				25 150			50 8000	μA
Holding current	I_H			6		25		100		mA
Latching current	I_L	$t_p = 10$ μs $I_G = 0,3$ A $di_G/dt = 0,3$ A/μs				25		150		mA
Gate trigger voltage	V_{GT}			6		25			1,5	V
Gate trigger current	I_{GT}			6		25			55	mA
Gate non-trigger current	I_{GD}					25			3000	nA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,02		K/W
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Rectifier Diode

Static

Forward voltage	V_F				80	25 125 150		1,27 1,27	1,33 ⁽¹⁾ 1,31 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1600$ V				25 150			20 1500	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						0,96		K/W
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⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

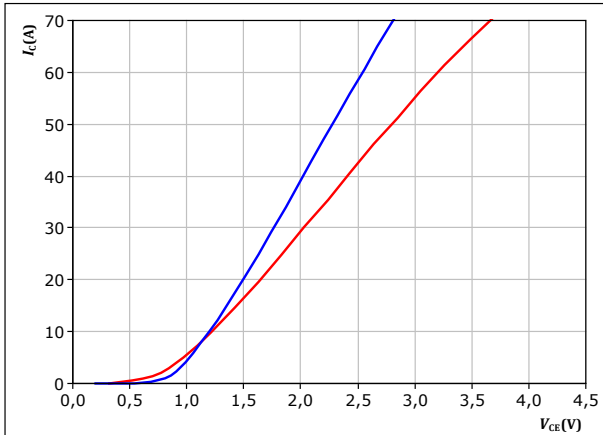


Brake Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

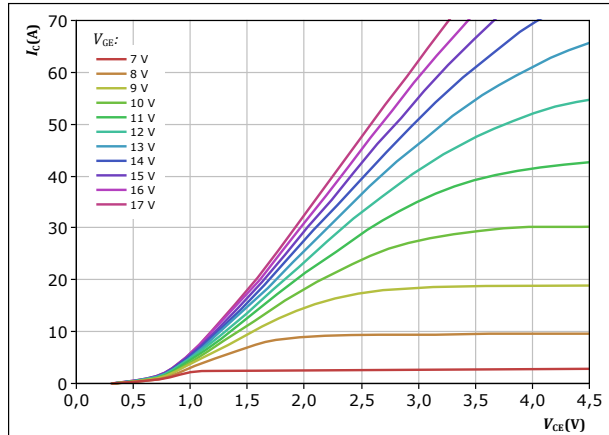


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25^\circ C$ (blue line)
 $125^\circ C$ (red line)

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

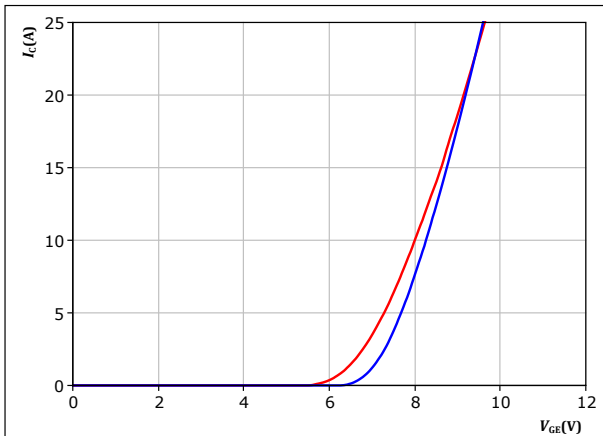


$t_p = 250 \mu s$
 $T_j = 125^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

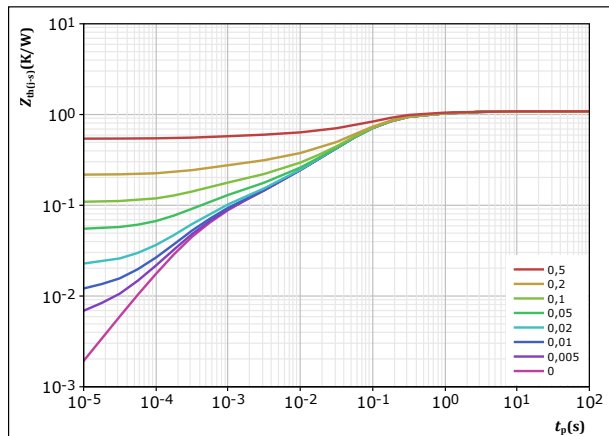


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25^\circ C$ (blue line)
 $125^\circ C$ (red line)

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,084 K/W$

IGBT thermal model values

R (K/W)	τ (s)
8,51E-02	1,82E+00
2,15E-01	2,53E-01
5,88E-01	7,31E-02
1,01E-01	9,54E-03
4,27E-02	1,52E-03
5,22E-02	3,55E-04

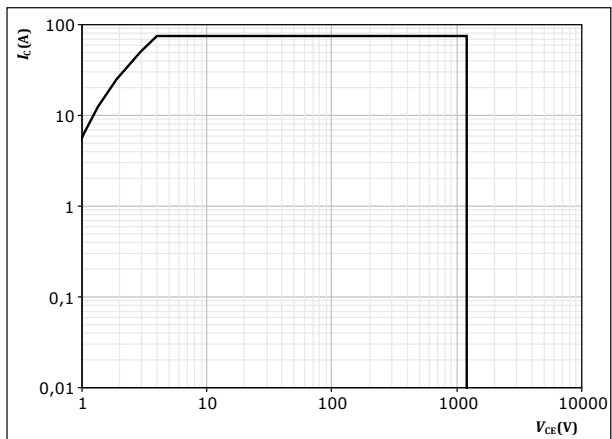


Brake Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



$D =$ single pulse

$T_s = 80$ °C

$V_{CE} = 15$ V

$T_j = T_{jmax}$

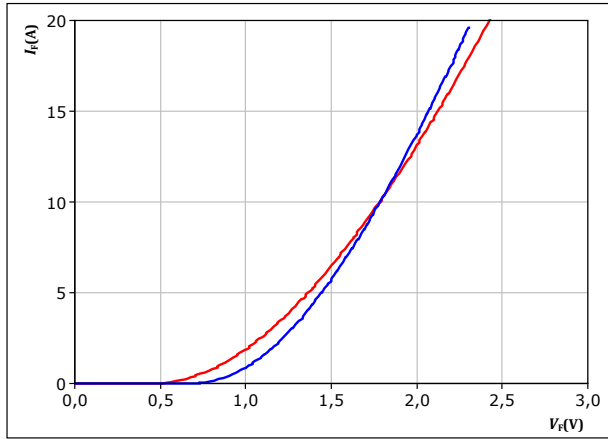


Brake Diode Characteristics

figure 6. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

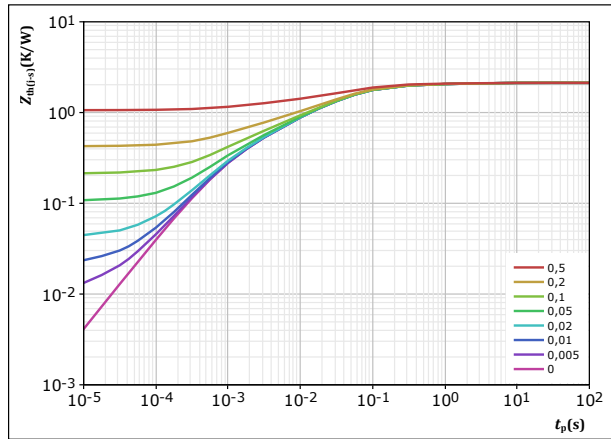


$t_p = 250 \mu s$
 T_j : — 25 °C
 — 125 °C

figure 7. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 2,124 \text{ K/W}$
 FWD thermal model values

R (K/W)	τ (s)
7,00E-02	3,23E+00
1,48E-01	4,03E-01
7,34E-01	6,67E-02
5,90E-01	2,04E-02
3,47E-01	4,32E-03
2,36E-01	8,05E-04

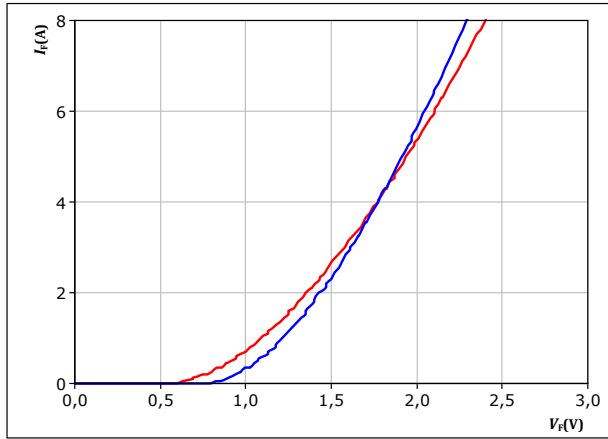


Brake Sw. Protection Diode Characteristics

figure 8. FWD

Typical forward characteristics

$$I_F = f(V_F)$$



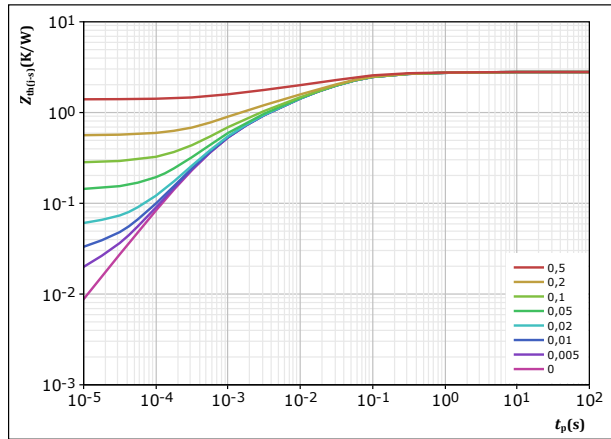
$t_p = 250\ \mu\text{s}$

$T_j:$ — 25 °C
— 125 °C

figure 9. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$

$R_{th(j-s)} = 2,796\ \text{K/W}$

FWD thermal model values

R (K/W)	τ (s)
7,82E-02	2,45E+00
1,95E-01	2,65E-01
9,84E-01	4,77E-02
6,58E-01	1,23E-02
5,09E-01	2,70E-03
3,71E-01	5,98E-04



Rectifier Thyristor Characteristics

figure 10. Thyristor

Typical forward characteristics

$$I_F = f(V_F)$$

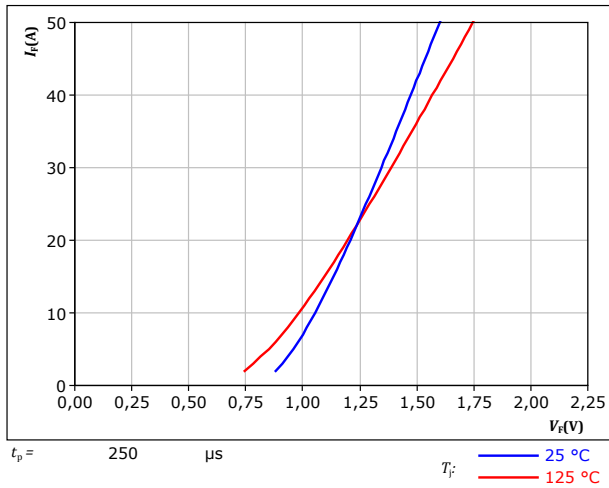
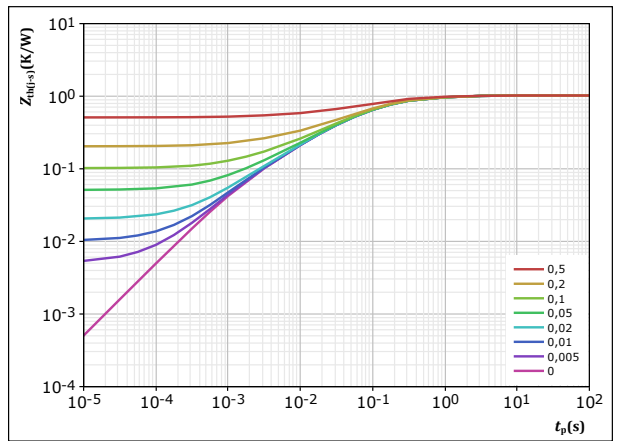


figure 11. Thyristor

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$$D = \frac{t_p}{T} = 1,022 \text{ K/W}$$

Thyristor thermal model values

R (K/W)	τ (s)
1,01E-01	1,45E+00
2,12E-01	2,65E-01
4,76E-01	7,87E-02
1,89E-01	1,28E-02
4,45E-02	1,54E-03



Rectifier Diode Characteristics

figure 12. Rectifier

Typical forward characteristics

$$I_F = f(V_F)$$

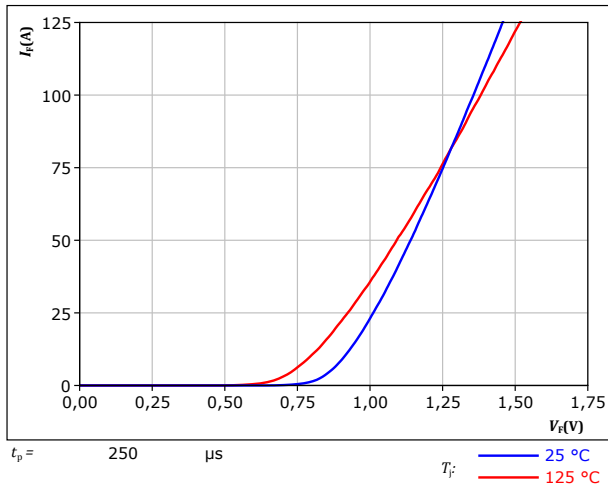
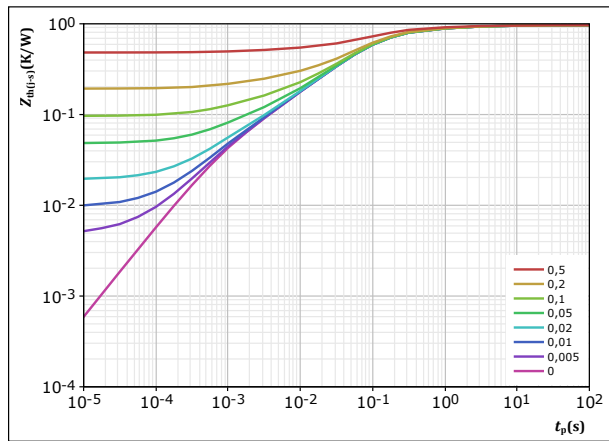


figure 13. Rectifier

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = \frac{t_p}{T}$
 $R_{th(j-s)} = 0,965 \text{ K/W}$
 Rectifier thermal model values

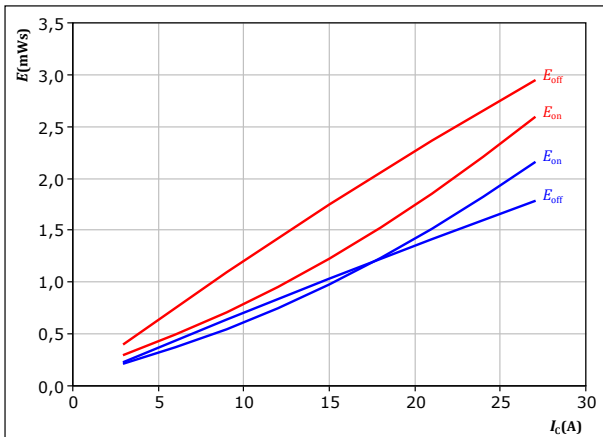
R (K/W)	τ (s)
3,98E-02	7,88E+00
1,29E-01	8,64E-01
4,20E-01	1,32E-01
2,76E-01	4,24E-02
6,63E-02	5,80E-03
3,37E-02	8,90E-04



Brake Switching Characteristics

figure 14. IGBT

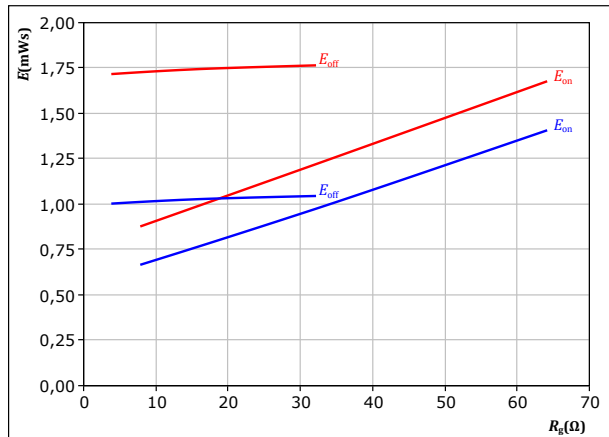
Typical switching energy losses as a function of collector current
 $E = f(I_c)$



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω
 $R_{goff} = 16$ Ω
 T_j : — 25 °C
— 125 °C

figure 15. IGBT

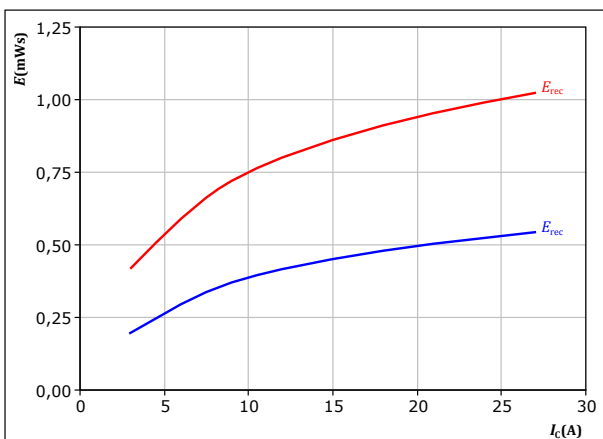
Typical switching energy losses as a function of IGBT turn on gate resistor
 $E = f(R_g)$



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A
 T_j : — 25 °C
— 125 °C

figure 16. FWD

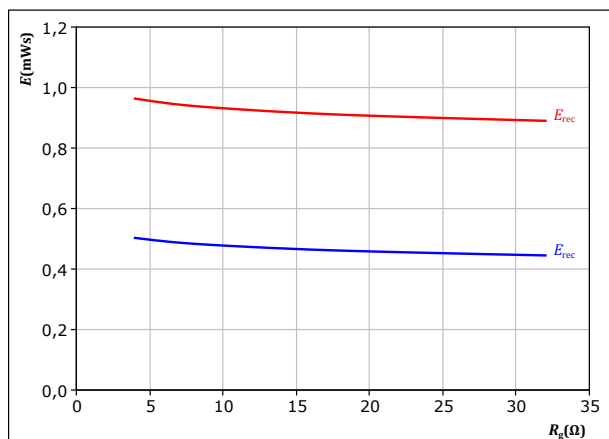
Typical reverse recovered energy loss as a function of collector current
 $E_{rec} = f(I_c)$



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω
 T_j : — 25 °C
— 125 °C

figure 17. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor
 $E_{rec} = f(R_g)$



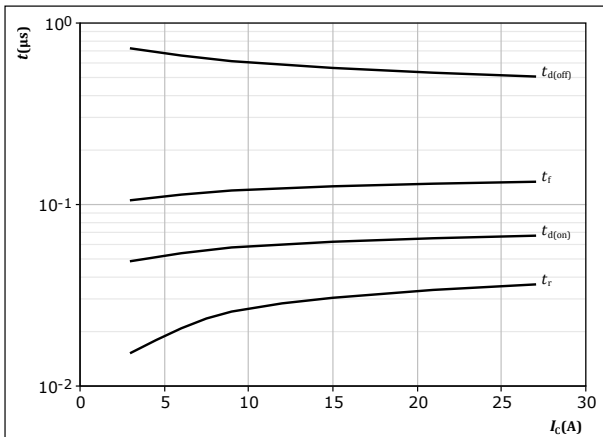
With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A
 T_j : — 25 °C
— 125 °C



Brake Switching Characteristics

figure 18. IGBT

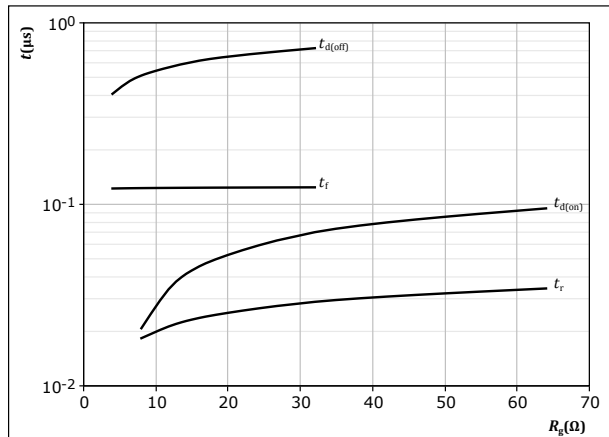
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 125$ °C
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω
 $R_{goff} = 16$ Ω

figure 19. IGBT

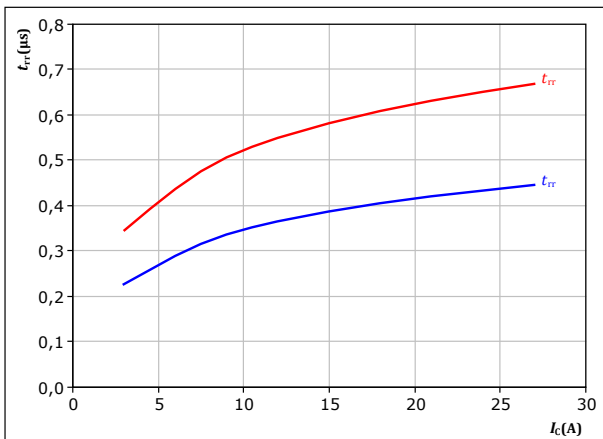
Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 125$ °C
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

figure 20. FWD

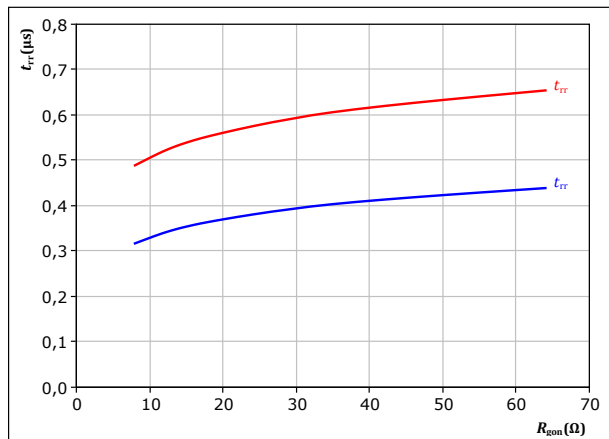
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω
 T_j : — 25 °C
— 125 °C

figure 21. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A
 T_j : — 25 °C
— 125 °C

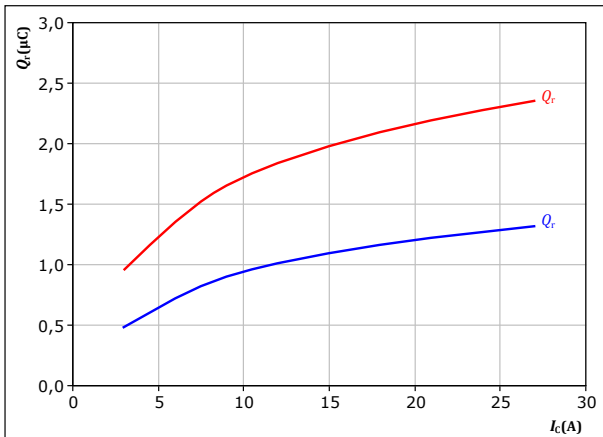


Brake Switching Characteristics

figure 22. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

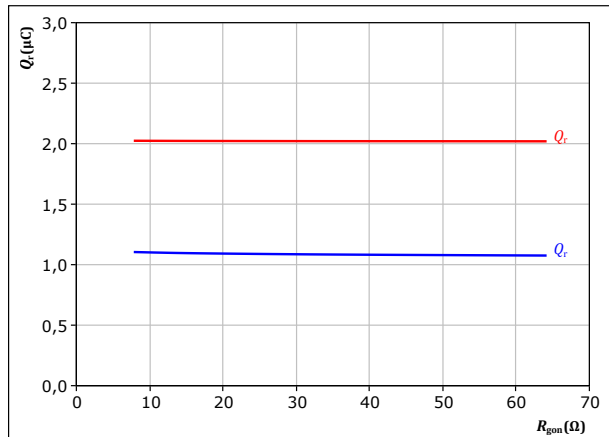
$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω

T_j : — 25 °C
— 125 °C

figure 23. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

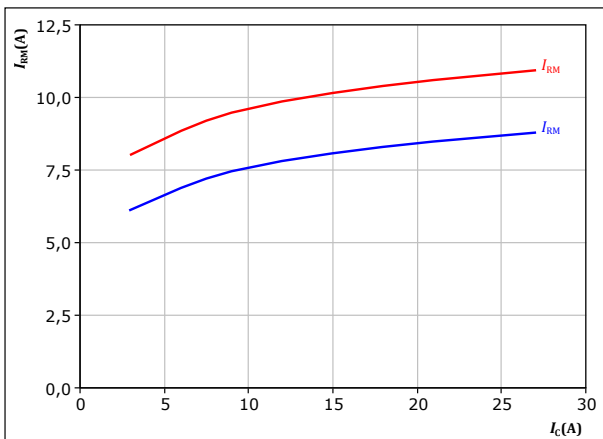
$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

T_j : — 25 °C
— 125 °C

figure 24. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

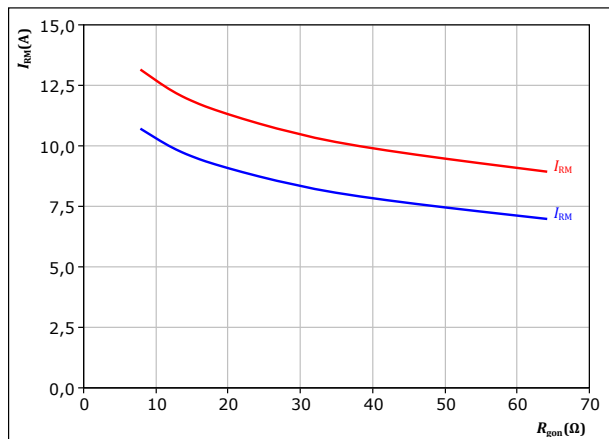
$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω

T_j : — 25 °C
— 125 °C

figure 25. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

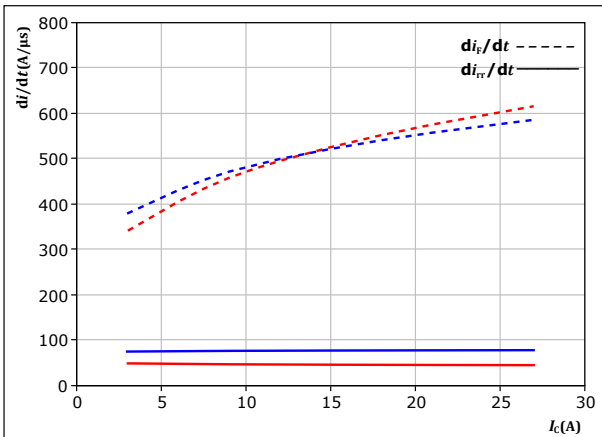
T_j : — 25 °C
— 125 °C



Brake Switching Characteristics

figure 26. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_c)$



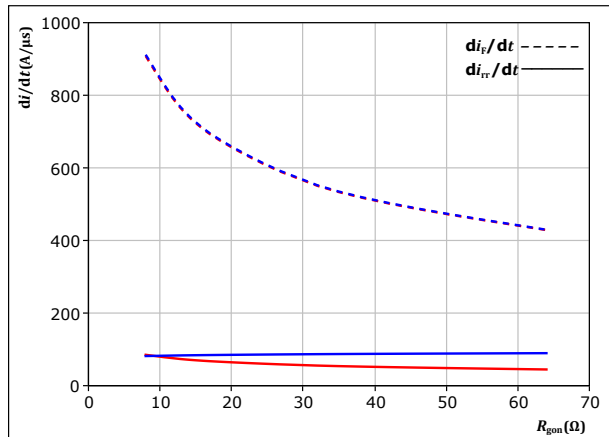
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 32$ Ω

T_j : — 25 °C
 — 125 °C

figure 27. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{gon})$



With an inductive load at

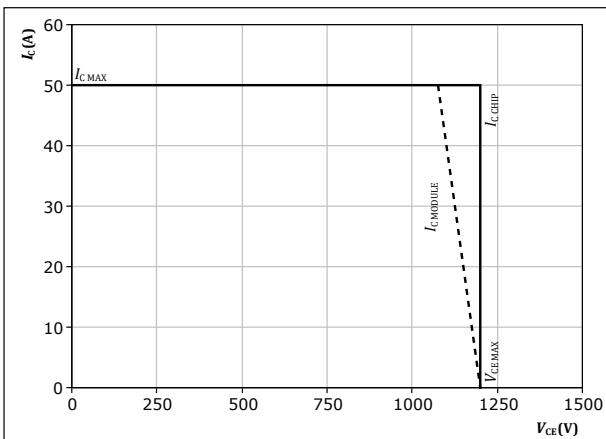
$V_{CE} = 600$ V
 $V_{GE} = 0/15$ V
 $I_c = 15$ A

T_j : — 25 °C
 — 125 °C

figure 28. IGBT

Reverse bias safe operating area

$I_c = f(V_{CE})$



At $T_j = 125$ °C
 $R_{gon} = 32$ Ω
 $R_{goff} = 16$ Ω



Brake Switching Definitions

figure 29. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

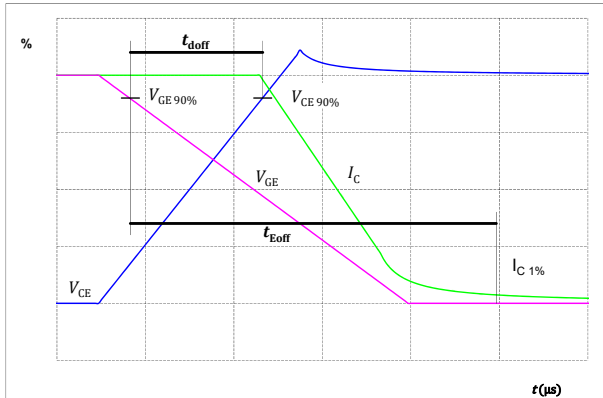


figure 30. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

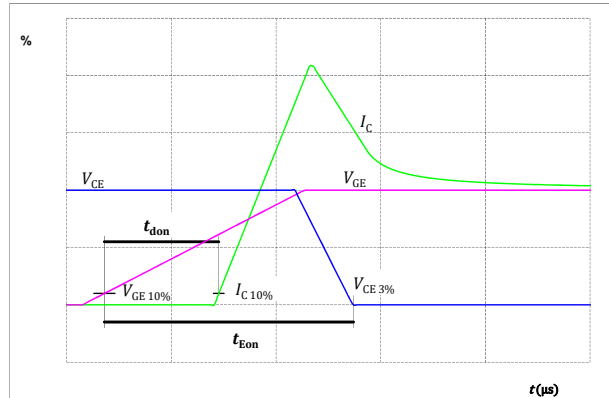


figure 31. IGBT

Turn-off Switching Waveforms & definition of t_f

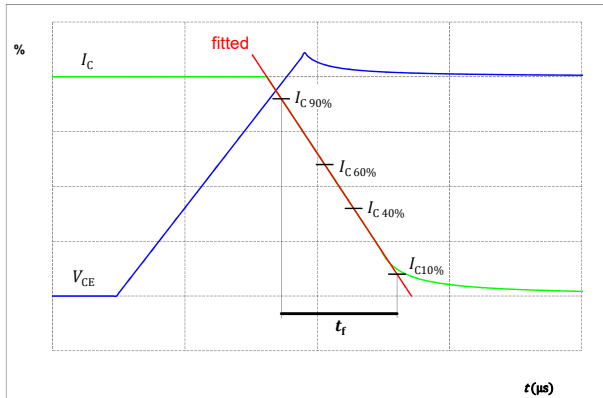
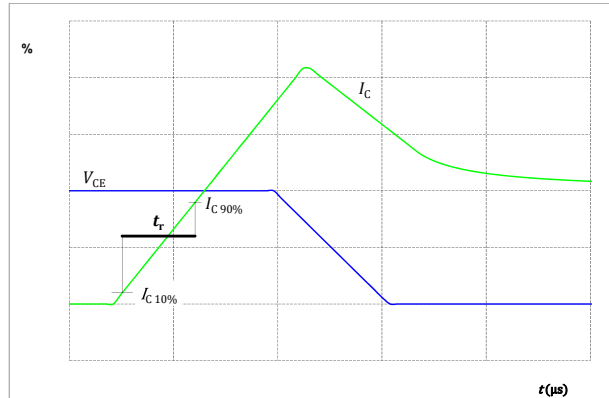


figure 32. IGBT

Turn-on Switching Waveforms & definition of t_r





Brake Switching Definitions

figure 33. FWD

Turn-off Switching Waveforms & definition of t_{rr}

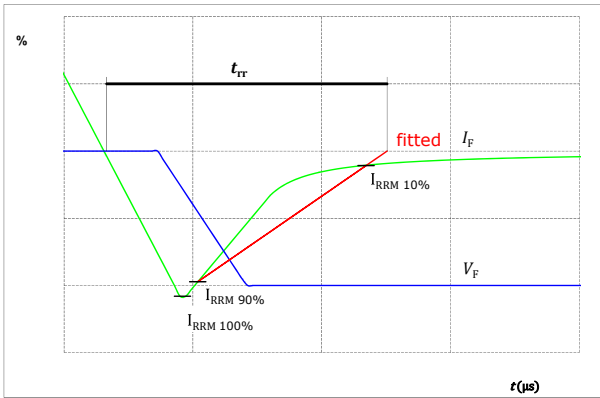
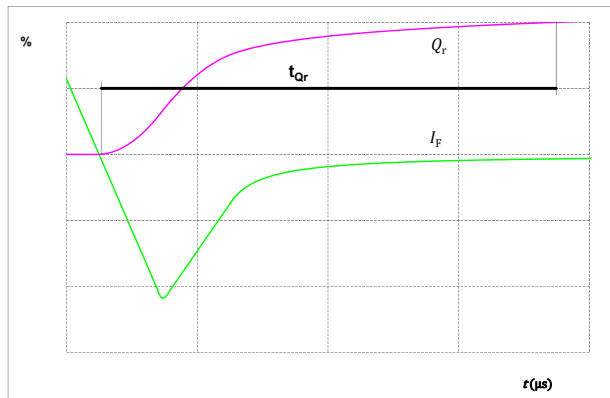


figure 34. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





Vincotech

V23990-P717-G10-PM
datasheet

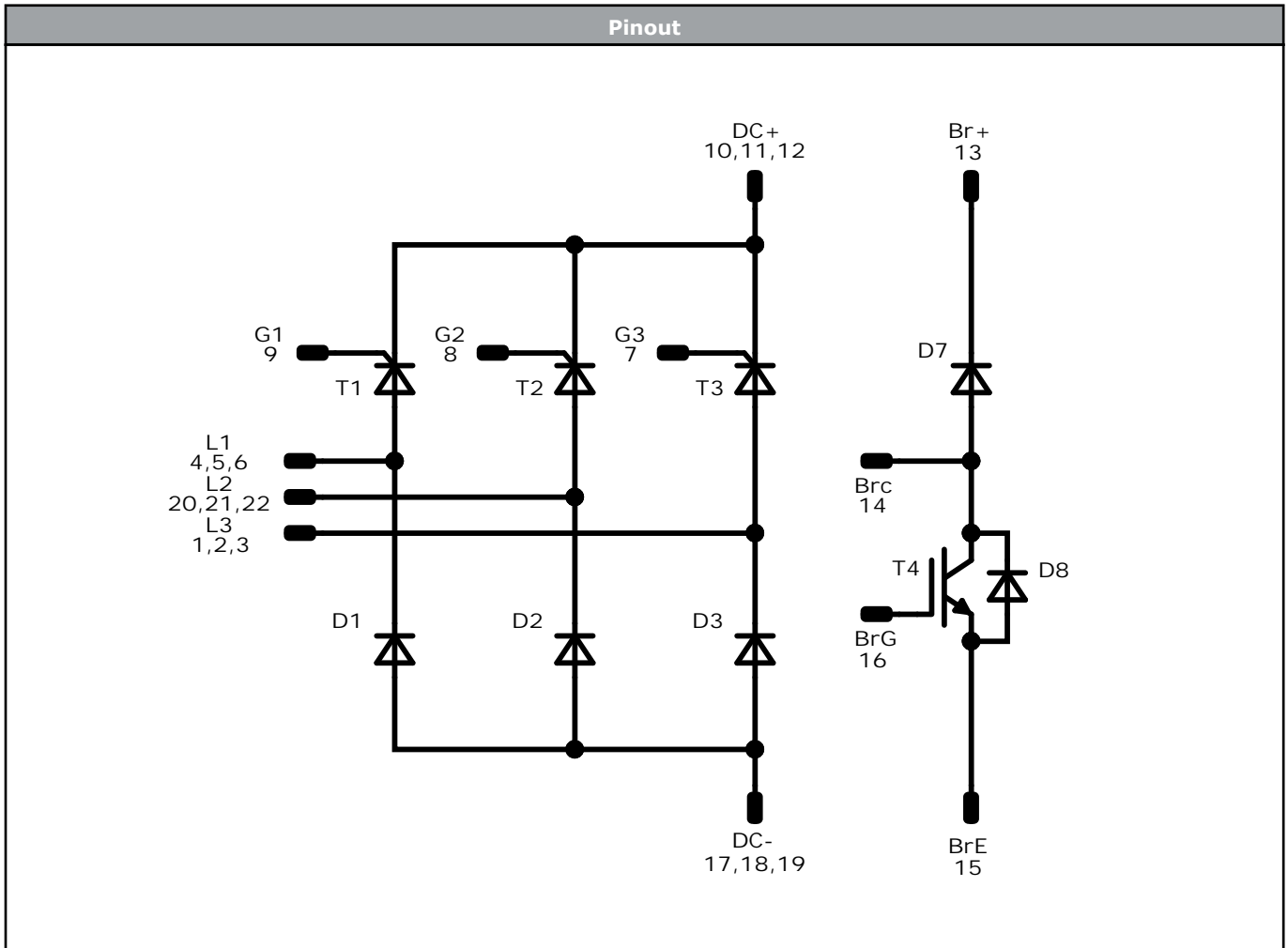
Ordering Code	
Version	Ordering Code
Without thermal paste	V23990-P717-G10-PM
With thermal paste (3,4 W/mK, PSX-P7)	V23990-P717-G10-/3/-PM

Marking							
	Text	VIN	Date code	Type&Ver	UL	Lot	Serial
		VIN	WWYY	TTTTTTV	UL	LLLLL	SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code		
		TTTTTTV	LLLLL	SSSS	WWYY		

Pin table [mm]			
Pin	X	Y	Function
1	53	0	L3
2	50,1	0	L3
3	47,2	0	L3
4	40,2	0	L1
5	37,3	0	L1
6	34,4	0	L1
7	27,4	0	G3
8	24,5	0	G2
9	21,6	0	G1
10	18,7	0	DC+
11	15,8	0	DC+
12	12,9	0	DC+
13	7,1	0	Br+
14	0	0	BrC
15	0	7	BrE
16	3	7	BrG
17	7	7	DC-
18	9,9	7	DC-
19	12,8	7	DC-
20	44	7	L2
21	47	7	L2
22	50	7	L2

Outline

Tolerance of positions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance



Identification					
ID	Component	Voltage	Current	Function	Comment
T4	IGBT	1200 V	25 A	Brake Switch	
D7	FWD	1200 V	7,5 A	Brake Diode	
D8	FWD	1200 V	3 A	Brake Sw. Protection Diode	
T1, T2, T3	Thyristor	1200 V	45 A	Rectifier Thyristor	
D1, D2, D3	Rectifier	1600 V	42 A	Rectifier Diode	




Packaging instruction				
Standard packaging quantity (SPQ) 80	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for <i>flow90</i> 1 packages see vincotech.com website.

Package data
Package data for <i>flow90</i> 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-P717-G10-PM-D5-14	13 Aug. 2022	New Datasheet format, module is unchanged Introduce Rth values with PSX-P7 Updated dynamic characteristic Separate datasheet	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.